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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

May 2014

FCA36N60NF

N-Channel SupreMOS® FRFET® MOSFET

600 V, 34.9 A, 95 mΩ

Features

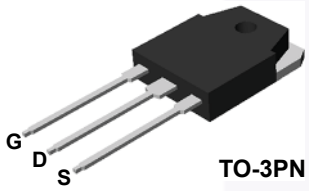
- $R_{DS(on)}$ = 80 mΩ (Typ.) @ V_{GS} = 10V, I_D = 18 A
- Ultra Low Gate Charge (Typ. Q_g = 86 nC)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)}$ = 338 pF)
- 100% Avalanche Tested
- RoHS Compliant

Application

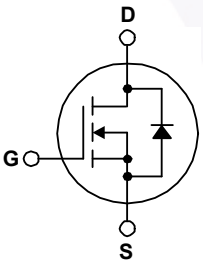
- Solar Inverter
- AC-DC Power Supply

Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SupreMOS FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.



TO-3PN



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FCA36N60NF	Unit
V_{DSS}	Drain to Source Voltage			600	V
V_{GSS}	Gate to Source Voltage			±30	V
I_D	Drain Current	Continuous (T_C = 25°C)		34.9	A
		Continuous (T_C = 100°C)		22	
I_{DM}	Drain Current	Pulsed	(Note 1)	104.7	A
E_{AS}	Single Pulsed Avalanche Energy		(Note 2)	1800	mJ
I_{AR}	Avalanche Current		(Note 1)	12	A
E_{AR}	Repetitive Avalanche Energy		(Note 1)	3.12	mJ
dv/dt	MOSFET dv/dt			100	V/ns
	Peak Diode Recovery dv/dt		(Note 3)	50	
P_D	Power Dissipation	(T_C = 25°C)		312	W
		Derate Above 25°C		2.6	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FCA36N60NF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.40	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink, Typ.	0.24	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA36N60NF	FCA36N60NF	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 1 mA, V_{GS} = 0 V, T_J = 25°C	600	-	-	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 1 mA, Referenced to 25°C	-	0.60	-	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 480 V, V_{GS} = 0 V	-	-	10	μA
		T_J = 125°C	-	-	100	
I_{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA	3.0	3.7	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 18 A	-	80	95	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 20 V, I_D = 18 A	-	39	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 100 V, V_{GS} = 0 V, f = 1 MHz	-	3191	4245	pF
C_{oss}	Output Capacitance		-	145	195	pF
C_{rss}	Reverse Transfer Capacitance		-	5	8	pF
C_{oss}	Output Capacitance	V_{DS} = 380 V, V_{GS} = 0 V, f = 1 MHz	-	81	-	pF
C_{oss}eff.	Effective Output Capacitance	V_{DS} = 0 V to 480 V, V_{GS} = 0 V	-	338	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	V_{DS} = 380 V, I_D = 18 A, V_{GS} = 10 V (Note 4)	-	86	112	nC
Q_{gs}	Gate to Source Gate Charge		-	16	-	nC
Q_{gd}	Gate to Drain “Miller” Charge		-	36	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	1.2	-	Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 380 V, I_D = 18 A, V_{GS} = 10 V, R_G = 4.7 Ω (Note 4)	-	27	64	ns
t_r	Turn-On Rise Time		-	17	44	ns
$t_{d(off)}$	Turn-Off Delay Time		-	92	194	ns
t_f	Turn-Off Fall Time		-	4	18	ns
Drain-Source Diode Characteristics						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	36	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	108	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 18 A	-	-	1.2	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_{SD} = 18 A, dI_F/dt = 100 A/μs	-	166	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.3	-	μC

Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{AS} = 12 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 36 A, di/dt ≤ 1200 A/μs, V_{DD} = 380 V, starting T_J = 25°C.
4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

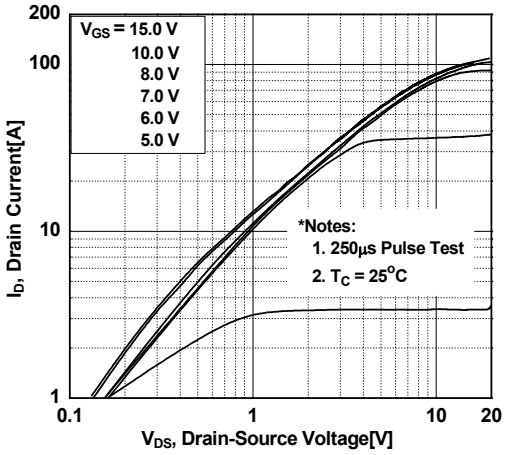


Figure 2. Transfer Characteristics

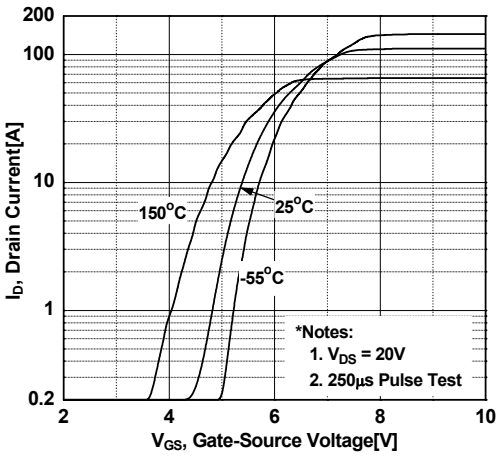


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

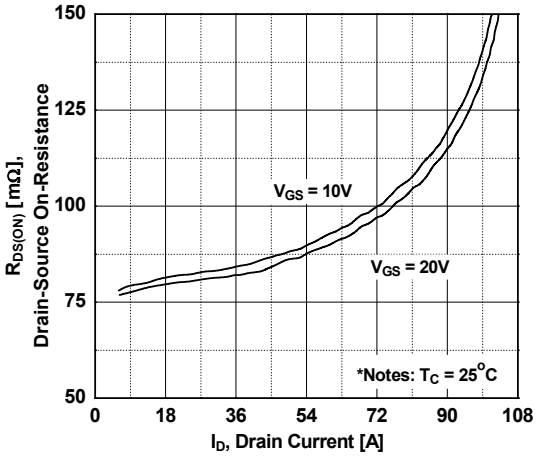


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

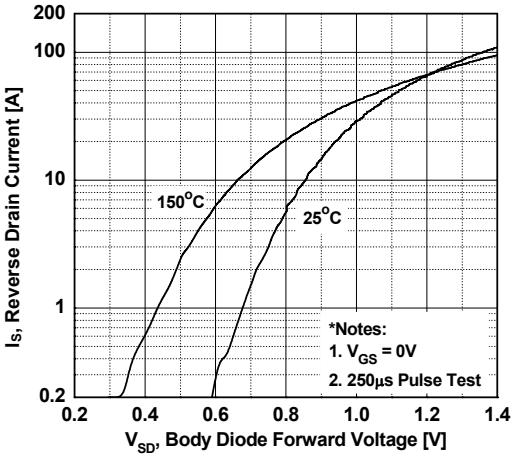


Figure 5. Capacitance Characteristics

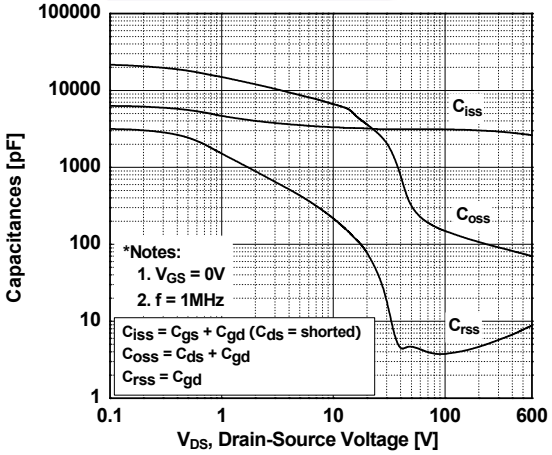
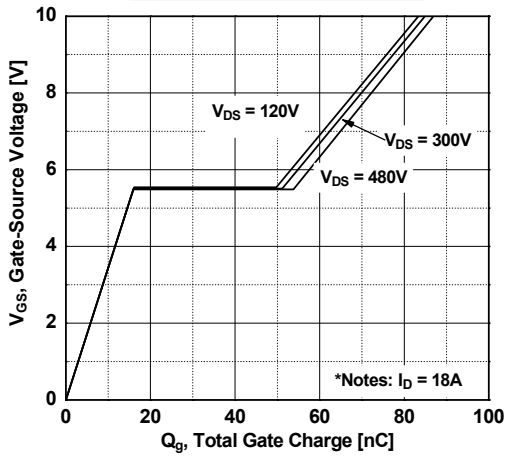


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

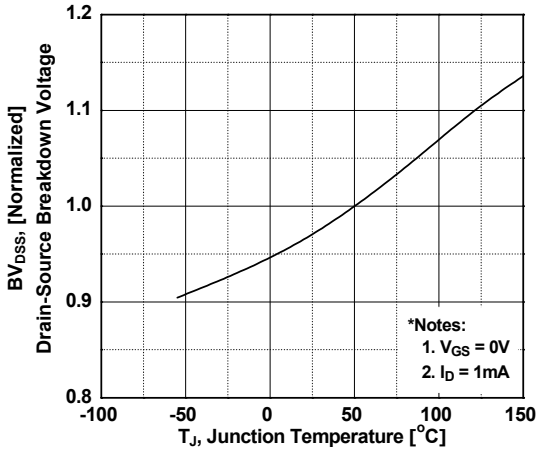


Figure 8. On-Resistance Variation vs. Temperature

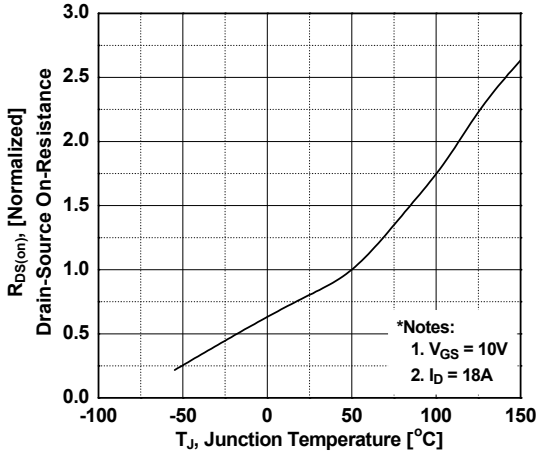


Figure 9. Maximum Safe Operating Area

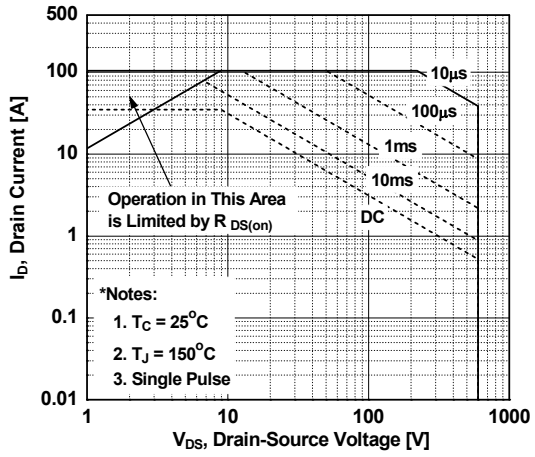


Figure 10. Maximum Drain Current vs. Case Temperature

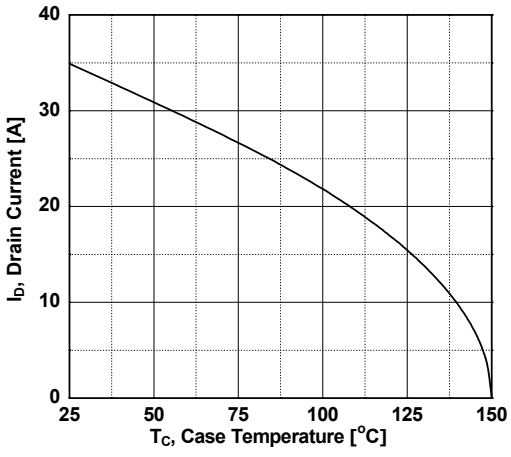
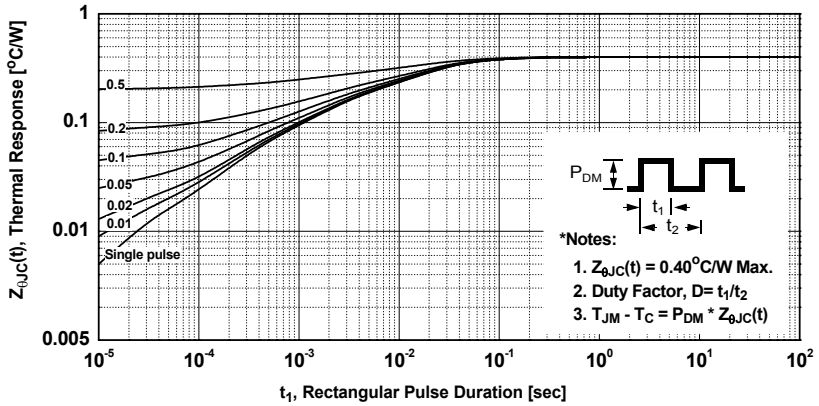


Figure 11. Transient Thermal Response Curve



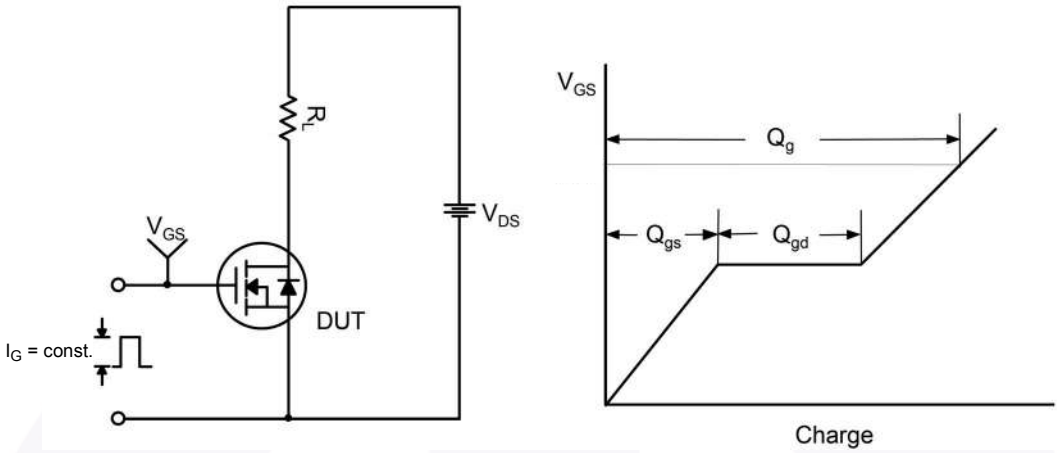


Figure 12. Gate Charge Test Circuit & Waveform

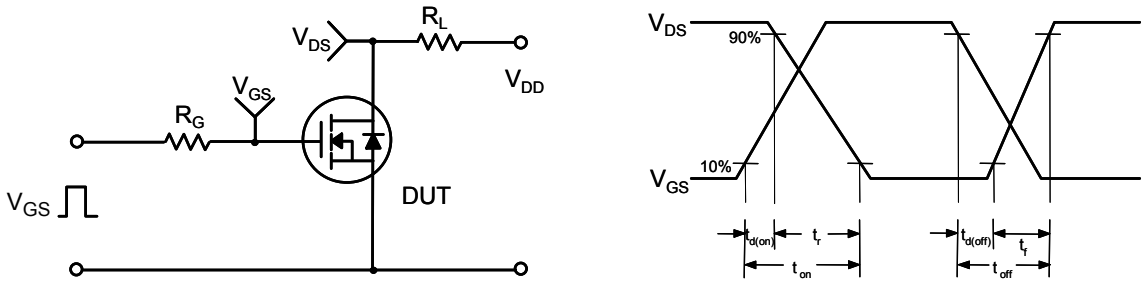


Figure 13. Resistive Switching Test Circuit & Waveforms

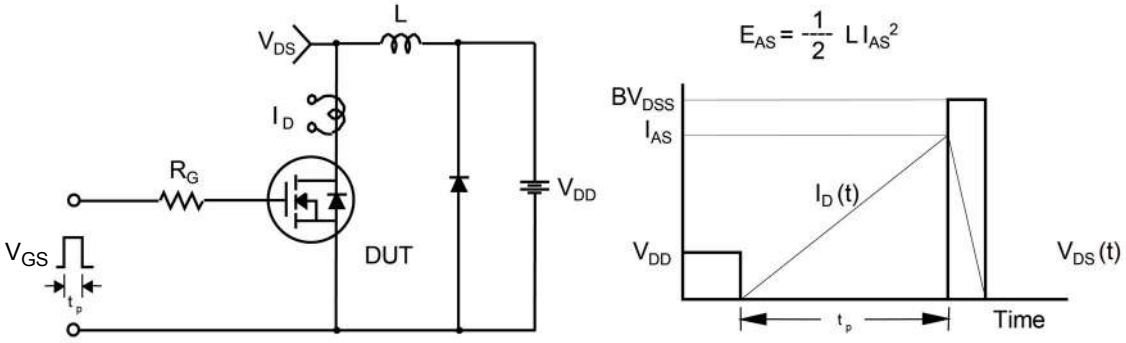


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

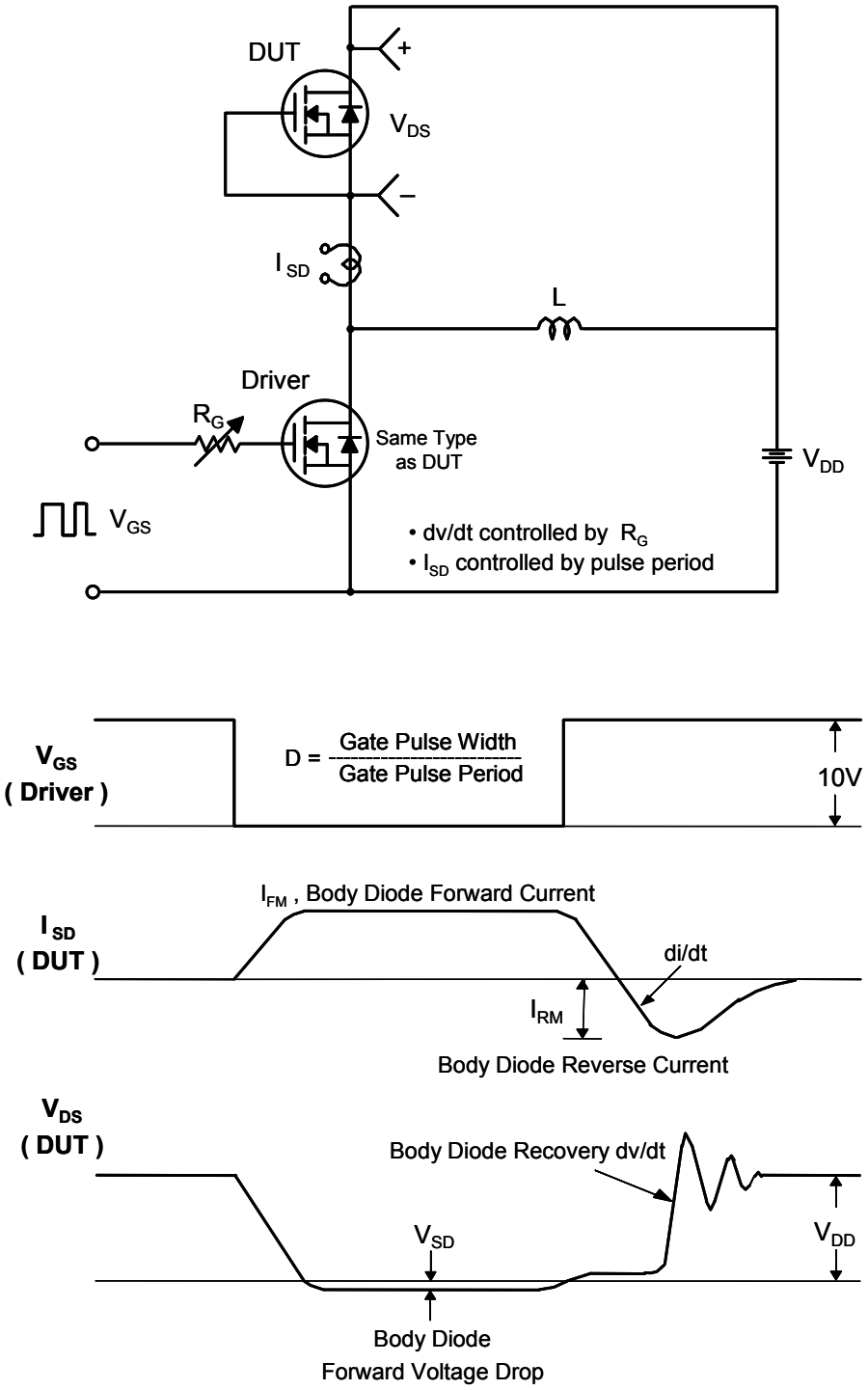
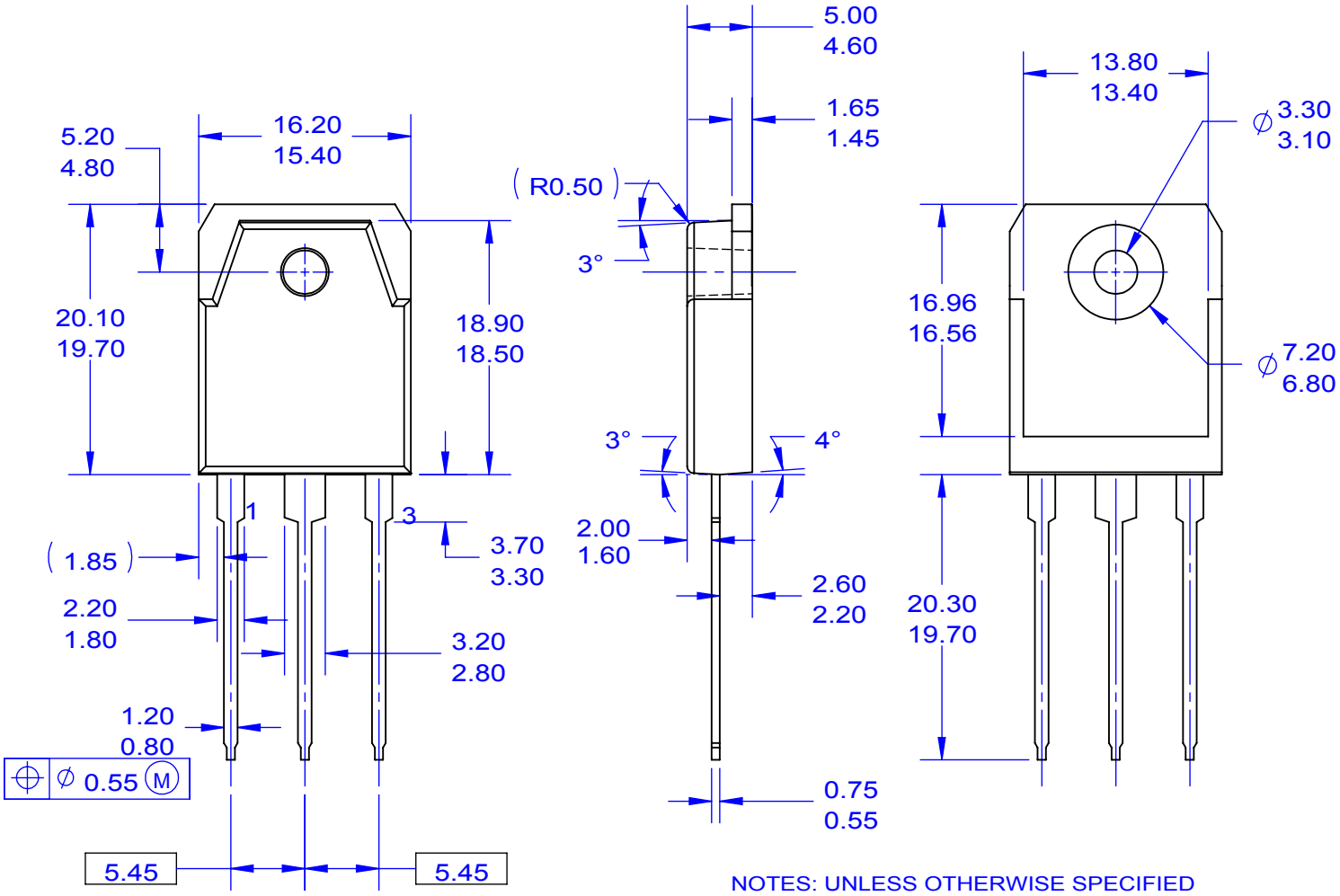
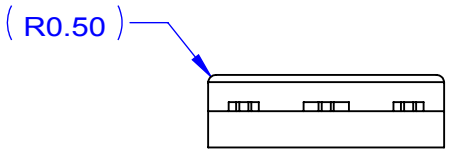


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





NOTES: UNLESS OTHERWISE SPECIFIED

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B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
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